

## **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)

2. (Currently Amended) The conductive bump of Claim 1, wherein A conductive bump for a semiconductor chip that has a pad-mounting surface which is provided with at least a bonding pad thereon, said conductive bump comprising:

a first metal layer adapted to be bonded to the bonding pad;

a conductive paste body formed on said first metal layer; and

a second metal layer formed on said paste body such that said paste body is sandwiched between said first and second metal layers;

said first metal layer also has a base portion bonded to said bonding pad, and a peripheral portion extending from said base portion in a transverse direction relative to said base portion and cooperating with said base portion to confine a recess therebetween, said conductive paste body filling said recess, said recess being closed by said second metal layer.

3.-4. (Canceled).

5. (Currently Amended) The conductive bump of claim 2[[1]], wherein said conductive paste comprises a thermosetting resin and a conductive filler.

6. (Canceled).